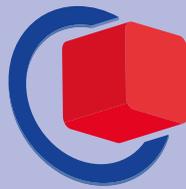


Nuremberg, Germany  
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Prof. Dr.-Ing. Axel Sikora  
Chairman of embedded world Conference

## ***embedded world Conference 2019*** **– Embedded Intelligence**

Now in its 17th year, the embedded world Conference takes up the title of one of its precursors from the 1990s. Back then “Embedded Intelligence” was rather a vision of the future but now it is increasingly becoming reality and shaping more and more systems: from autonomous vehicles over image recognition and embedded vision systems to preventive and demand-driven maintenance in Industry 4.0 systems, from small edge computers to high-performance cloud servers. These developments not only open up immense possibilities and business opportunities, but are also closely associated with many technical, economic, social and ethical issues.

With a program of high-quality and solution-oriented presentations, the embedded world Conference 2019 aims to contribute once more to the success of an industry that has now become an essential part of the technological future and, as such, a basis for our continued economic success.

The embedded world Conference 2019 is made up of 10 subject areas, which are clearly structured in the program and presented in different colors. These are: 1. Internet of Things, 2. Connected Systems, 3. Embedded OS, 4. Safety & Security, 5. Hardware Engineering, 6. Software &

Systems Engineering, 7. Embedded Vision, 8. Autonomous & Intelligent Systems, 9. Embedded GUI & HMI, and 10. System-on-Chip. The solution-oriented presentations of each session build upon one another and examine questions from different perspectives. Discussion and an active exchange of ideas with the speakers as well as among conference participants are encouraged. The 30-minute presentations of the sessions will be complemented by 12 classes, which provide comprehensive basic information on selected topics in the form of condensed training courses.

It is not possible to describe all 250 presentations in detail here. You will find them fully explained on the following pages of this booklet.

The steering board of the embedded world Conference 2019 wishes all participants stimulating discussions about new ideas and solutions in order to be able to cope more easily and better with the immense challenges that lie ahead. You are welcome to gain great insights in a pulsating atmosphere.



Prof. Dr.-Ing. Axel Sikora  
Chairman of embedded world Conference

# CONFERENCE PROGRAM

	1. Internet of Things – Platforms & Applications	2. Connected Systems		3. Embedded OS			4. Safety & Security	
<b>DAY 1:</b> morning		Session 2.1: Communication I CAN	Session 2.2: Communication II Bluetooth	Session 3.1: OS Basics	Class 3.1: The Robert Berger Class: Embedded Linux – a Crash Course		Session 4.1 I: HW-based Security I	Session 4.2: Functional Safety
<b>DAY 1:</b> afternoon		Session 2.3: Communication III Realtime & TSN		Session 3.2: OSADL			Session 4.1 II: HW-based Security II	
<b>DAY 2:</b> morning	Session 1.1 I: IoT I	Session 2.4: Communication IV Wireless Physical & Design Aspects		Session 3.3: Linux	Class 3.2: Embedded Android Workshop		Session 4.3 I: Security Architectures & Hacking I	Class 4.1: The ESCRYPT Class
<b>DAY 2:</b> afternoon	Session 1.1 II: IoT II	Session 2.5: Communication V Wireless Multiprotocol		Session 3.4: Virtualization		Class 3.3: Linux Hands-on Workshop with BeagleBoard.org PocketBeagle	Session 4.3 II: Security Architectures & Hacking II	
<b>DAY 3:</b> morning	Session 1.2: IoT III	Session 2.6 I: NB-IoT & LPWA I	Session 2.8 I: Wireless Power I	Session 3.5: OS-Security	Class 3.4: The Mc Guire Class: Introduction to Linux Kernel Tools		Session 4.4 I: Securing IoT I	
<b>DAY 3:</b> afternoon	Session 1.3: IoT IV OPC UA I 4.0	Session 2.6 II: NB-IoT & LPWA II	Session 2.8 II: Wireless Power II				Session 4.4 II: Securing IoT II	Class 4.2: Hands-on Side Channel Power Analysis
		Session 2.7: Communication VI Wireless Localization						

## KEYNOTE-SPEAKERS



**Jim Tung, MathWorks**

**Conference Keynote:** Developing Game-Changing Embedded Intelligence  
February 26th, 2019, 1:30 PM

Jim Tung is a MathWorks Fellow, focusing on business and technology strategy and working with key customers and partners. Jim has more than 35 years of experience in real-time systems, data acquisition, and technical computing, including 30 years at MathWorks. Jim was previously vice president of marketing and vice president of business development at MathWorks, and earlier held marketing and sales management positions at Lotus Development and Keithley DAS, a pioneering manufacturer of PC-based data acquisition systems.



**Jean-Marc Chery, STMicroelectronics**

**Conference Keynote:**  
**Embedded Intelligence for the Next Wave of Smart Systems – Opportunities and Challenges on the Edge**  
February 27th, 2019, 1:30 PM

Jean-Marc Chery is STMicroelectronics' President and Chief Executive Officer since May 31st, 2018. In July 2017 Chery had been appointed Deputy CEO of ST with overall responsibility for Technology and Manufacturing, as well as for Sales and Marketing operations. Before that, he had held a broad range of management positions across ST functions throughout his career. Chery currently chairs the board of directors of STS, ST's manufacturing joint venture in China, and is a board member of the European microelectronics R&D program AENEAS.

5. Hardware Engineering		6. Software & Systems Engineering				7. Embedded Vision	8. Autonomous & Intelligent Systems	9. Embedded GUI & HMI	10. System-on-Chip
Session 5.1: RISC-V I Overview	Class 5.1: Ultra Low Power	Session 6.1: SW-Engineering I Languages & Standards	Session 6.2 I: MISRA I	Class 6.1: The Bruce Douglass Class 1: Modeling		Session 7.1 I: Embedded Vision I	Session 8.1: Intelligent Systems I Applications		
Session 5.2: RISC-V II Security			Session 6.2 II: MISRA II			Session 7.1 II: Embedded Vision II		Session 8.2: Intelligent Systems II Hardware	Session 9.1: Embedded GUI & HMI
Session 5.3: RISC-V III System									
Class 5.2: RISC-V Workshop I		Session 6.3: SW-Engineering II Design & Modeling	Class 6.2: The Bruce Douglass Class 2 Agile				Session 8.3: Intelligent Systems III Autonomous Driving	Session 10.1: SoC I Analog Circuits & Solutions Session 10.2 I: SoC II EDA I	
Session 5.4: Power Supply		Session 6.4: SW-Engineering III SW-Quality I					Session 8.4: Intelligent Systems IV Development Methods	Session 10.2 II: SoC II EDA II	
		Session 6.5: SW-Engineering IV Development Process	Session 6.7: SW-Engineering VI SW-Testing	Class 6.3: The Bruce Douglass Class 3 Safety & Security	Class 6.4: The Greg Davis Class C / C++			Session 10.3: SoC III Complex Ics & System Solutions	
		Session 6.6: SW-Engineering V SW-Quality II	Session 6.8: SW-Engineering VII SW-Debugging					Session 10.4: SoC IV ICs & IPs	



Frank Riemenschneider, Publication Chair

Registered participants of the ewC2019 will receive the conference proceedings with the papers of selected contributions free of additional charge after the conference. The proceedings of ewC2018 reached nearly 1,000 pages with more than 170 papers.



STEERING BOARD

- back row (from left to right):  
 Dr. Bernd Hense,  
 Prof. Dr. Axel Sikora,  
 Dr. Klaus Grimm
- front row:  
 Joachim Kroll,  
 Prof. Dr. Peter Fromm

	<b>Session 2.1: Communication I CAN</b>	<b>Session 3.1: OS Basics</b>	<b>Session 4.1 I: HW-based Security I</b>	<b>Session 4.2: Functional Safety</b>
09:30-10:00	<b>Troubleshooting in Embedded Networks Based on CANopen FD</b> Reiner Zitzmann, CAN in Automation	<b>Introduction to OpenAMP: An Open Source Standard and API for Asymmetric Multiprocessing Systems</b> Jeffrey Hancock, Mentor, A Siemens Business	<b>Hardware Security for Embedded Systems</b> Ben Boehman, Advanced Micro Devices (AMD)	<b>High Performance Distributed Mixed Criticality Systems to SIL2</b> Prof. Hans Dermot Doran, Zürich University of Applied Sciences
10:00-10:30	<b>Automated Node ID Assignment in CAN and CAN(FD) Networks</b> Christian Keydel, Olaf Pfeiffer, Embedded Systems Academy			
10:30-11:00	<b>Signal Improvement Concept for CAN FD Networks</b> Yao Yao, CAN in Automation	<b>42 Reasons Using FreeRTOS Should Scare Developers</b> Jacob Beningo, Beningo Embedded Group	<b>Transitioning from Software Based Security to Hardware Based Security – How to Make the Leap</b> Anthony Ambrose, Data I/O	<b>Modeling and Assessment of Safety Critical Systems</b> Thomas Barth, Hochschule Darmstadt
11:00-11:30	Coffee Break			
11:30-12:00	<b>Session 2.2: Communication II Bluetooth</b>	<b>How to Measure RTOS Performance</b> Colin Walls, Mentor, A Siemens Business	<b>Making Products Safer and More Secure with an MPU</b> Jean Labrosse, Silicon Labs	<b>Safety Critical RTOS: Adapting Across Applications</b> Andrew Longhurst, WITTENSTEIN high integrity systems
	<b>Bluetooth Evolution</b> Jim Katsandres, Bluetooth SIG			
12:00-12:30	<b>Supercharging BLE Beacons with Bluetooth 5</b> Joe Tillison, Silicon Labs	<b>Home-grown or Commercial Linux: a Binary Choice?</b> Iisko Lappalainen, MontaVista Software	<b>Extend MCU Security Capabilities Beyond Trusted Execution with Hardware Crypto Acceleration and Asset Protection</b> Saurin Choksi, NXP Semiconductors	<b>Data and Control Coupling: Taint Analysis for Critical Embedded Applications</b> Mark Pitchford, LDRA
12:30-13:30	Lunch Break			
13:30-14:30	<div style="display: flex; align-items: center; justify-content: center;"> <div style="background-color: red; color: white; border-radius: 50%; padding: 10px; margin-right: 20px; text-align: center;"> <b>KEYNOTE</b> 13:30         </div> <div style="text-align: center;"> <p><b>Conference Keynote:</b>  <b>Developing Game-Changing Embedded Intelligence</b>            Jim Tung, MathWorks</p> </div> </div>			
	<b>Session 2.3: Communication III Real-Time &amp; TSN</b>	<b>Session 3.2: OSADL</b> powered by 	<b>Session 4.1 II: HW-based Security II</b>	
14:30-15:00	<b>Real-time Control of Embedded Devices with OPC UA Pub/Sub w, w/o TSN</b> Heinrich Munz, KUKA	<b>Performance of Real-time Computing and Real-time Network Communication Using the Linux Mainline Kernel in the OSADL QA Farm</b> Dr. Carsten Emde, OSADL	<b>What Can You Do When You Don't Trust Your Processor?</b> Yoni Kahana, Nanolock security	
15:00-15:30	<b>TSN – a Pragmatic Approach</b> Michael Roeder, SILICA - Avnet EMG	<b>Safe and Secure Field Updates of Embedded Linux Systems</b> Enrico Jörns, Pengutronix	<b>Methods for Provisioning Security Features in a Cortex-M33 based MCU Using a Physically Unclonable Function</b> Rob Cosaro, NXP Semiconductors	
15:30-16:00	Coffee Break			
16:00-16:30	<b>Time Sensitive Networking for Industry 4.0 and Automotive</b> Dr. Dadmehr Rezaei, Christian Albrecht, Intel	<b>Using Linux in Safety-critical Environments: Update on the SIL2LinuxMP Project</b> Prof. Nicholas Mc Guire, OpenTech EDV Research	<b>Securing IoT-Edge Devices and Node with Hardware-based Security</b> Timo Grassmann, Infineon Technologies	
16:30-17:00	<b>Extending Time Sensitive Networking over Next Generation Wi-Fi</b> Ritu Sethi, Intel	<b>Basics of Copyright Law and Open Source Licensing: Fulfilling License Obligations is Easier Than You May Think</b> Dr. Carsten Emde, OSADL	<b>TBA</b> Mayank Sharma, ARM	
17:00-17:30	<b>SPICE Simulation of 100Base-TX LAN-Transformer in an Ethernet Transmission Path</b> Simon Mark, Würth Elektronik eiSos	<b>OSS Compliance Tools</b> Dr. Michael Jaeger, Software Compliance Academy	<b>Secure Boot of a Complex Quad Core CPU</b> Bashar Aziz, Microchip Technology	
17:30-18:00		<b>How to Implement Appropriate Processes for License Compliance?</b> Dr. Catharina Maracke, Software Compliance Academy		

<b>Session 5.1: RISC-V I Overview</b> <b>RISC-V; Practical Industry Approach to Getting Started with This Technology</b> Prof. Robert Oshana, NXP Semiconductors	<b>Session 6.1: SW-Engineering I Languages &amp; Standards</b> <b>Declarative Programming for Cortex-M Class Embedded Devices</b> Andy Walter, macio	<b>Session 7.1 I: Embedded Vision I</b> <b>Adding Intelligent Vision to Your Next Embedded Product</b> Radhika Jagtap, ARM	<b>Session 8.1: Intelligent Systems I Applications</b> <b>The Edge is Getting Smarter – AI in the IoT World</b> Amir Sherman, Arrow
<b>How to Benefit from RISC-V Based Linux for Embedded Industrial Applications</b> Krishnakumar R, Microchip Technology	<b>Navigating the Jungle of the Secure Coding Standards</b> Michal Rozenau, Parasoft	<b>Implementation of Camera Based Driver Monitoring System Using Deep Learning</b> Nirmal Kumar Sancheti, AllGo Systems	<b>Context-Aware Smart Home – Opening the Eyes of AI in the Home Through Sensors</b> Johan Pedersen, Silicon Labs
<b>The Soul of a New SoC: Hands-on Experience with Embedding a RISC-V Core</b> Onno Martens, Trinamic Motion Control	<b>Session 6.2 I: MISRA I</b> <b>The MISRA C Coding Standard: A Key Enabler for the Development of Safety- and Security-Critical Embedded Software</b> Prof. Dr. Roberto Bagnara, BUGSENG & University of Parma	<b>Develop Multi-platform Computer Vision Solution with Intel Up Squared</b> Oluwatobi Oyinlola, Intel	<b>Ultra Low Power Key Phrase Detection at the Edge</b> Hussein Osman, Lattice Semiconductor

Coffee Break

<b>Methodology for Implementation of Custom Instructions in the RISC-V Architecture</b> Larry Lapides, Imperas Software	<b>MISRA C/C++ Situation Report</b> Andrew Banks, LDRA	<b>High Image Quality for Embedded Vision Applications</b> Henning Haider, Allied Vision Technologies	<b>Embedded Deep Learning Healthcare Collaboration System</b> Chungyeh Wang, Intel
<b>Compliance Methodology and Initial Results for RISC-V ISA Implementations</b> Lee Moore, Imperas Software	<b>Writing Reliable Code with MISRA C</b> Colin Walls, Mentor, A Siemens Business	<b>Machine Learning for Embedded; a System of Software and Hardware Components</b> Prof. Robert Oshana, NXP Semiconductors	<b>Motor Condition Monitoring for Predictive Maintenance in „Industrie 4.0“</b> Volker Rzehak, Texas Instruments

Lunch Break

**Conference Keynote:**  
**Developing Game-Changing Embedded Intelligence**  
 Jim Tung, MathWorks

<b>Session 5.2: RISC-V II Security</b> <b>Maintaining Security In a Heterogeneous and Changing World</b> Jon Geater, Thales Cesare Garlati, prpl	<b>Session 6.2 II: MISRA II</b> <b>Using MISRA C/C++ for Security and Reliability</b> Greg Davis, Green Hills Software	<b>Session 7.1 II: Embedded Vision II</b> <b>Deep Learning Versus Rule-based-configurable Vision Software on Embedded Devices</b> Christoph Wagner, MVTec Software	<b>Session 8.2: Intelligent Systems II Hardware</b> <b>How to Implement Deep Learning on FPGAs</b> Robert Green, Asic Design Services	<b>Session 9.1: Embedded GUI &amp; HMI</b> <b>Which Graphic Software Library Should I Use for My Embedded Device?</b> Aurindam Jana, The Qt Company
<b>A New Zero-Trust Model For Securing Embedded Systems</b> Chris Conlon, wolfSSL Cesare Garlati, prpl	<b>Avoiding Unsafe and Insecure Complex Software</b> Mark Richardson, LDRA	<b>Sorting Through the Many Options for Machine Learning at the Edge</b> Markus Levy, NXP Semiconductors	<b>Machine Learning on Arm Cortex-M Microcontrollers</b> Dr. Naveen Suda, ARM	

Coffee Break

<b>Session 5.3: RISC-V III System</b> <b>User Mode Interrupts: A Must for Securing Embedded Systems</b> Prof. Sandro Pinto, Uni do Minho Cesare Garlati, prpl	<b>Why Coding Standards and Implementing MISRA-C</b> Chris Hills, Phaedrus Systems	<b>Enhance Human Vision with Intel Vision Technology</b> Pavani Kilari, Intel	<b>Accelerating Next Generation Deep Learning Algorithms – How to Choose FPGA or GPU?</b> Prof. Alok Gupta, Intel	<b>Embedded Computer Vision Applications with Qt</b> Berthold Krevet, basysKom
<b>Embracing a System Level Approach: Combining Arm &amp; RISC-V in Heterogeneous Designs</b> Gajinder Panesar, UltraSoC	<b>How Far Can You Trust Your Compiler?</b> Mark Pitchford, LDRA	<b>Implementing Monocular Visual SLAM for Augmented Reality in Low-Power Embedded Vision Systems</b> Gordon Cooper, Synopsys	<b>Hardware Implementation of Deep Neural Networks – A Comparison Between FPGA and GPU</b> Marcus Rüb, Hahn-Schickard	<b>3D GUIs for the Mass Market</b> Jason Williamson, Altia
<b>RISC-V: High Performance Embedded SweRV Core Microarchitecture, Performance and Implementation Challenges</b> Dr. Zvonimir Bandic, Western Digital	<b>Approaches for Improving Handling of Static Analysis Findings</b> Dr. Claude Bolduc, Rogue Wave Software	<b>Bridging Embedded Vision and Machine Vision with a Hybrid Driver</b> Mark Schenk, Allied Vision Technologies	<b>Driving Deep Learning Performance Through Hardware Accelerators and Advanced Storage Technology</b> Muhammad Waqas Sadiq Jutt, Intel	<b>The Usage and Benefits of Global Palettes in Embedded Graphics Applications</b> Kurt Parker, Microchip Technology
	powered by 			

	Session 1.1 I: Internet of Things I	Session 2.4: Communication IV Wireless Physical & Design Aspects	Session 3.3: Linux	Session 4.3 I: Security Architectures & Hacking I
09:30-10:00	<b>Session Keynote: Digital Transformation: A Catalyst for Changing the Embedded Development Paradigm</b> Dr. Gareth Noyes, Wind River Systems	<b>Model Based Approach for Wireless Network Design and Implementation</b> Marco Roggero, MathWorks	<b>ARM SoCs in the Mainline Linux Kernel</b> Arnd Bergmann, Linaro	<b>Lessons to be Learnt from the World's Most Lethal Cyber-Attacks</b> Anyck Turgeo, IBM
10:00-10:30	<b>Think Local: How to Migrate Intelligence from the Cloud to Embedded Devices at the Edge</b> Chris Shore, ARM	<b>Robust Software Defined COFDM-Modem for Embedded Applications</b> Andreas Bayer, A.R. Bayer DSP Systeme	<b>Status of the Embedded GPU Space</b> Robert Foss, Collabora	<b>Quantum Computers Just Broke My Crypto – What Now?</b> Kris Chaplin, Intel
10:30-11:00	<b>The Future of IoT: Edge Intelligence, Distributed Processing and Data Orchestration</b> Olivier Amiot, Sierra Wireless	<b>From DC to Daylight: Single Chip RF Solutions for Wired, Wireless and High Frequency Applications</b> Glenn Steiner, Xilinx	<b>Fast Path in Embedded Networking</b> Luka Perkov, Sartura	<b>Breaking Security: Power Analysis &amp; Fault Injection Attacks</b> Dr. Colin O'Flynn, NewAE Technology/Dalhousie University
11:00-11:30	Coffee Break			
11:30-12:00	<b>Where the Cloud Meets the Edge</b> Andreas Burghart, Digi International Richard Elberger, AWS	<b>How a Software-defined Radio Enables Diversity in IoT Endpoint Design</b> Dan Clement, ON Semiconductor	<b>Software Defined Peripherals in Linux Using Zephyr and RPMsg</b> Marek Novak, NXP Semiconductors	<b>Developing a Mixed-critical AUTOSAR Adaptive ECU with Safety and Security by Design</b> Dr. Sergey Tverdyshev, SYSGO
12:00-12:30	<b>Distributed Database Systems and Edge/Fog/Cloud Computing</b> Steve Graves, McObject	<b>Introduction for Bluetooth5 IoT Device – RoKi Sensor Node</b> Koki Okada, ROHM Semiconductor	<b>Linux Containers on a Small Device – a Good Idea?</b> Valter Minute, Toradex	<b>Enabling TPM2.0 with an Open Source Software Stack for Industrial and Automotive Applications</b> Dr. Florian Schreiner, Infineon Technologies
12:30-13:30	Lunch Break			
13:30-14:30	<div style="display: flex; align-items: center; justify-content: center;">  <div> <p style="text-align: center;"><b>Conference Keynote:</b>  <b>Embedded Intelligence for the Next Wave of Smart Systems – Opportunities and Challenges on the Edge</b>                      Jean-Marc Chery, STMicroelectronics</p> </div> </div>			
	Session 1.1 II: Internet of Things II	Session 2.5: Communication V Wireless Multiprotocol	Session 3.4: Virtualization	Session 4.3 II: Security Architectures & Hacking II
14:30-15:00	<b>Databases at the Edge – ObjectBox for Devices and Gateways</b> Markus Junginger, Objectbox	<b>The Benefits and Challenges of a Common Software Platform for IoT Development</b> David Egan, Silicon Labs	<b>Virtualization Impact on the Performance in Embedded Systems</b> Marcus Nissemark, Green Hills Software	<b>Secure Boot, Chain of Trust and Data Protection</b> Akshay Bhat, Timesys
15:00-15:30	<b>A Validation Methodology for Edge Computing Gateway with IPv6 based Wireless Mesh Sensor Network Technology</b> Usman Sarwar, Intel	<b>Radio Scheduling in Dynamic Multiprotocol Applications</b> Marius Munder, Silicon Labs	<b>On the Road Towards Autonomous Driving – Simplifying AI with Virtualization Technologies</b> Dr. Ciwan Gouma, OpenSynergy	<b>Chains of Trust: Building Security into Today's Digital World</b> Gil Bernabeu, GlobalPlatform
15:30-16:00	Coffee Break			
16:00-16:30	<b>Streaming Analytics Framework (SAF)</b> Dr. Shao-Wen Yang, Dr. Wendy Siew Wen Chin, Intel	<b>Low Power WiFi for IoT Devices</b> Uri Weinrib, Texas Instruments	<b>The Automotive GPU gets Virtual</b> Kristof Beets, Imagination Technologies	<b>Sidestepping Side Channel Attacks Through Separation &amp; Virtualization</b> Arun Subbarao, Lynx Software Technologies
16:30-17:00	<b>Towards a Greener World with ECMA-393 Network Proxying: A Practical Guide To Support Multi-Protocols Network Presence</b> Boon Leong Ong, Intel	<b>Manage Thousands of Nodes Through Secure Commissioning with Thread 1.2 Network Protocol</b> Antonio Concio, NXP Semiconductors	<b>Handling Mixed Criticality on Modern Multi-core Systems: the HERCULES Project</b> Dr. Paolo Gai, Evidence	<b>Securing all Network Layers of CAN (FD) Communication</b> Olaf Pfeiffer, Embedded Systems Academy Andreas Walz, HS Offenburg
17:00-17:30	<b>Applying Cognitive Systems Engineering to Shape a Good Developer Experience of IoT Solutions</b> Dr. Jongsoon Park, Intel	<b>Taking Mesh Networking Mainstream</b> William Hart, Particle Industries	<b>New Development Paradigms for Smart IoT</b> Loïc Minier, Canonical	<b>Simplifying Product Returns Through Device Security</b> Øivind Loe, Silicon Labs

	<b>Session 6.3: Software Engineering II Design &amp; Modeling</b>	<b>Session 8.3: Intelligent Systems III Autonomous Driving</b>	<b>Session 10.1: SoC I Analog Circuits &amp; Solutions</b>
	<b>Migrating Legacy Software Applications to Model-Based and AUTOSAR: an Introduction to a Programmatic Approach</b> Roberto Agnelli, Teoresi	<b>Law and Innovation – a Difficult Relationship?</b> Susanne Meiners, NewTec	<b>A Programmable Analog Computer on a Chip</b> Dr. Nicolas Clauvelin, John Miliios, Sendyne
	<b>Emerging MultiCore Development Paradigms</b> Greg Davis, Green Hills Software	<b>Performance Profiling and Optimization for Autonomous Driving Workload</b> Yang Wang, Intel	<b>Mission Impossible? If an Embedded Antenna Needs a Ground Plane of 100mm, How Can it Perform Brilliantly within an IoT Device with a Very Small PCB?</b> Colin Newman, Antenova
	<b>Coping with Complexity in Mobility by Connected Model-based Systems Engineering – An Insight Look Into Successful Projects</b> Andreas Korff, Parametric Technology	<b>A Machine Learning Environment for Evaluating Autonomous Driving Software</b> Jussi Hanhiova, Aalto University	<b>Protect the Ports!</b> George Slama, Wurth Elektronik eiSos

Coffee Break

	<b>Software Quality, Systemic Failure and Dual Modular Redundancy</b> Mark Pitchford, LDRA	<b>Power Efficient AI Processors for Perception and Decision Making in Autonomous Vehicles</b> Lazaar Louis, Cadence	<b>Session 10.2 I: SoC II EDA I</b>
	<b>Design Cycle Acceleration for Hardware/Software Co-Design with Renode</b> Steve Milburn, Dover Microsystems Michael Gielda, Antmicro	<b>Understanding the Safe Move to Intended Functionality in Autonomy</b> Joe Dailey, Siemens PLM Software	<b>Using Models for SoC Hardware/Software Co-design</b> Baruch Mitsengendler, MathWorks
			<b>Matlab Simulink for FPGA-Design</b> Dr. Baltasar Trancón Widemann, aicas

Lunch Break

**Conference Keynote:**

**Embedded Intelligence for the Next Wave of Smart Systems – Opportunities and Challenges on the Edge**

Jean-Marc Chery, STMicroelectronics

<b>Session 5.4: Power Supply</b>	<b>Session 6.4: Software Engineering III Software Quality I</b>	<b>Session 8.4: Intelligent Systems IV Development Methods</b>	<b>Session 10.2 II: SoC II EDA II</b>
<b>PoE: The Power Oriented Era</b> Jairo Bustos Heredia, Würth Elektronik eiSos	<b>Semantic Static Analysis of IoT Software</b> Dr. Pietro Ferrara, JuliaSoft	<b>Efficient Workflow for Designing, Training and Deploying Deep Learning Models with MATLAB</b> Marco Roggero, The MathWorks	<b>An Open Source Framework for Rapid Application Development for Complex SoCs</b> Anton Krug, Microchip Technology
<b>Extending the Abilities of Battery-Powered End Nodes Through Better Power Supply Design</b> Josh Norem, Silicon Labs	<b>Static Analysis of Finite State Machines with Zero False Alarms</b> Dr. Daniel Kästner, AbsInt Angewandte Informatik	<b>Accelerating Embedded Inferencing</b> Russell Klein, Mentor Graphics	<b>Delivering Real Time and Determinism with Zynq Ultrascale+ MPSoC A53 Clusters Using Advanced Cache Management, Jailhouse and Xen Hypervisor</b> Dr. Giulio Corradi, Xilinx

Coffee Break

<b>OP-TEE – A Intro to a Trusted Execution Environment</b> Andreas Schuler, Missing Link Electronics	<b>Machine Learning for Finding Programming Defects and Anomalies</b> Dr. Paul Anderson, GrammaTech	<b>Benchmarking the Intelligent Edge – A Framework to Measure Embedded AI Performance</b> Bruno Zimmermann, ZHAW InES	<b>System-Level Modeling of Heterogeneous Compute Architectures for NVMeExpress Protocol Acceleration</b> Cedrik Bock, Missing Link Electronics
<b>Harvesting Energy from RS232 Data Signals to Power a Wired to Wireless Converter</b> Prof. Dr. Marcel Meli, ZHAW InES	<b>How to Find Concurrency Issues in C and C++</b> Dr. Frank van den Beuken, Perforce Software	<b>Designing Intelligent Systems Using Resource Constrained Edge Devices</b> Jacob Beningo, Beningo Embedded Group	<b>Shifting-Left Together – Enabling the Ecosystem with Virtual Platforms</b> Dr. Jakob Engblom, Intel
<b>Ferrite for EMC – What Do I Need to Know?</b> George Slama, Wurth Elektronik eiSos	<b>Automating Code Reviews by Writing Your Own Program Analysis Rules</b> Prof. Dr. Ralf Huuck, Synopsys	<b>Safety in Cooperative Automated Systems</b> Dr. Daniel Schneider, Fraunhofer IESE	<b>Shift Left for Software Development Using Virtual Platform Emulation Hybrids</b> Frank Schirrmeyer, Cadence Design Systems

	Session 1.2: Internet of Things III	Session 2.6 I: NB-IoT & LPWA I	Session 2.8 I: Wireless Power I	Session 3.5: OS-Security
09:30-10:00	<b>IoT Platforms: Selection and Pitfalls</b> Jan Rodig, tresmo	<b>What 5G Can Help for Industrial IOT</b> Yongbin Wei, Qualcomm Technologies	<b>Market and Future of the Global Wireless Power Transfer Industry</b> Jörg Hantschel, Würth Elektronik eiSos	<b>The LTS Kernel is a Barrier to Building a Global Secure IoT Platform</b> George Grey, Foundries.io
10:00-10:30	<b>Benchmarks: the Good, the Bad, and the Ugly</b> Diego Buitrago, Ben Boren, Intel	<b>DECT-5G: Enhancing the DECT and ULE Standards to Embrace the Requirements of 5G (IMT-2020)</b> Daniel Hartnett, DECT Forum	<b>Qi Versus NFC: Evaluating NFC as a New Wireless Charging Solution for Small Battery Powered Devices</b> Peter Schmallegger, NXP Semiconductors Austria	<b>How Should an RTOS Works in a TrustZone for Armv8-M Environment?</b> Joseph Yiu, ARM
10:30-11:00	<b>How the Use the IIC's IICF to Select the Best IIoT Connectivity Technology</b> Brett Murphy, Real Time Innovations	<b>Evaluating NB-IoT Technology for Industrial Communication</b> Kofi Atta Nsiah, Hahn-Schickard	<b>EMF: Requirements, Directives and Measure Method in Europe</b> Werner Grommes, DGUV/IFA	<b>Designing a Secure and Reliable OTA Update Mechanism for IoT Endpoints</b> Nick Lethaby, Texas Instruments
11:00-11:30	Coffee Break			
11:30-12:00	<b>IoT Device Lifecycle Management – Update. Control. Secure. The Keys to IoT Device Best Performance and Secure Data-to-cloud Connections</b> Guillaume Djourabtchi, Gemalto	<b>LoRa LoRaWAN a Technologie Used in Industrial Application</b> Michael Fink, Semtech Germany	<b>15W Inductive Wireless Power Transfer with Integrated Data Communication</b> Cem Som, Würth Elektronik eiSos	<b>Android Security Internals</b> Karim Yaghmour, Opersys
12:00-12:30	<b>Improving Reliability of Industrial IoT Systems</b> Edwin de Jong, Real Time Innovations	<b>The 20 Cent IoT is Coming</b> Aurelius Wosylus, Sigfox Germany	<b>Boosting Contactless Charging to 40W</b> Francois Ricodeau, Semtech	<b>A Future-proof Performance Enhancement for Secure MCUboot</b> Derek Atkins, SecureRF
12:30-13:30	Lunch Break			
	Session 1.3: Internet of Things IV OPC UA I4.0	Session 2.6 II: NB-IoT & LPWA II	Session 2.8 II: Wireless Power II	
13:30-14:00	<b>Open Source OPC UA Pub/Sub Over TSN: Current Status and Implementation Plans</b> Julius Pfrommer, Fraunhofer IOSB	<b>Revolutionizing Worker Safety with Innovative IoT and LPWAN Solutions</b> Albert Behr, Behr Technologies	<b>Regulatory Requirements for Devices Using Wireless Power Transfer Technology</b> Niels Jeß, CETECOM	
14:00-14:30	<b>OPC UA Application Development with Open62541</b> Frank Meerkötter, basysKom	<b>Unified Test Environment for LPWA and Cellular IoT</b> Jubin E. Sebastian, Offenburg University of Applied Sciences	<b>Wireless Power Transfer Safety Test Toolkit: An Automated Tool for Compliance Testing of WPT Systems Including Implant Safety</b> Dr. Ilaria Liorni, IT'IS Foundation	
14:30-15:00	<b>Dynamic LWM2M Data Model Mapping to OPC UA</b> Dovydas Girdvainis, Hahn-Schickard	<b>Industrial Class LPWAN Protocol Stacks</b> David Rahusen, STACKFORCE	<b>Wireless Power Transfer in Rotating Assemblies</b> Jelena Mijuskovic, Würth Elektronik eiSos	
15:00-15:30	Coffee Break			
15:30-16:00	<b>Securing the IoT</b> Dorian Knoblauch, Fraunhofer FOKUS	<b>Session 2.7: Communication VI Wireless Localization</b>	<b>Wireless Power Transmission: High Efficient Solution Based on Resonance Effects with High Power Density for Long Transmission Distances</b> Günther Trautzi, WPT Systems	
16:00-16:30	<b>Assistance Systems for Industrial 4.0 Environments</b> Bjoern Barig, IMMS Kaja Balzereit, Fraunhofer IOSB-INA	<b>Introduction to UWB Network Topologies and Applications</b> Kenneth Dwyer, Decawave	<b>Cost Optimization in Wireless Power Systems</b> Christian Wern, etatronix	

<p><b>Session 4.4 I: Securing IoT I</b></p>	<p><b>Session 6.5: Software Engineering IV Development Process</b></p>	<p><b>Session 6.7: Software Engineering VI Software Testing</b></p>	<p><b>Session 10.3: SoC III Complex ICs &amp; System Solutions</b></p>
<p><b>Common Pitfalls in IoT Security Implementations and How to Avoid Them</b> Brent Wilson, Silicon Labs</p>	<p><b>Agile in Development Regarding Safety</b> Frank Poignée, infoteam Software</p>	<p><b>Self-testing in Embedded Systems</b> Colin Walls, Mentor, A Siemens Business</p>	<p><b>Next Generation 7nm FPGA Architecture Enables Machine Learning for Edge and Cloud Computing</b> Manoj Roge, Achronix Semiconductor</p>
<p><b>Security on IoT Devices with Secure Elements</b> Tobias Schläpfer, ZHAW Institute of Embedded Systems</p>	<p><b>Adopting Agile/DevOps ALM in Automotive &amp; Safety-critical Development</b> Peter Haller, Intland Software</p>	<p><b>Testing Strategies for Asymmetric Environments</b> Jeffrey Fortin, Vector Informatik</p>	<p><b>Design Space Exploration for Convolutional Neural Networks on a 22nm FD-SOI SoC</b> Nicolai Behmann, Leibniz Universität Hannover</p>
<p><b>Finding the Right Security Level for Your IoT Application</b> Dr. Lars Lydersen, Silicon Labs</p>	<p><b>How to Balance Traceability and Compliance With Agile Development</b> Robert Riccetti, Gerhard Kruger, Perforce Software</p>	<p><b>Testing Safety Critical Software Using Automated Fault Injection</b> Michael Wittner, Razorcat Development</p>	<p><b>High Performance Thermal Management Using Miniature Low Cost Microfluidics Heat Sink</b> Philippe Soussan, IMEC</p>
Coffee Break			
<p><b>TBA</b> Suresh Marisetty, ARM</p>	<p><b>Open Source Software and Mission-Critical Embedded Systems – Like Oil and Water</b> Andrew Banks, LDRA</p>	<p><b>Hardware in the Loop Test in Combination with Continuous Integration</b> Dr. Kristian Trenkel, iSyst Intelligente Systeme</p>	<p><b>400G+ Hyperscale Data Centers with 56G Ethernet PHY IP</b> Manmeet Walia, Synopsys</p>
<p><b>Secure Device Management for the Internet of Things</b> Geert-Jan Schrijen, Intrinsic ID</p>	<p><b>Bug-killing Using Best-practice Development Techniques</b> Mark Richardson, LDRA</p>	<p><b>Consistent Test Reuse Across MIL-&gt;SIL -&gt;HIL in a Model-Driven Development Workflow</b> Lance Brooks, Mentor, A Siemens Business</p>	<p><b>SSD SoC Microcontroller with Embedded Neural Network for 3D NAND Flash Memories</b> Dr. Lorenzo Zuolo, Microsemi</p>
Lunch Break			
<p><b>Session 4.4 II: Securing IoT II</b></p>	<p><b>Session 6.6: Software Engineering V Software Quality II</b></p>	<p><b>Session 6.8: Software Engineering VII Software Debugging</b></p>	<p><b>Session 10.4: SoC IV ICs &amp; IPs</b></p>
<p><b>Make Your IoT Project Secure in 5 Steps</b> Dr. Shawn Prestridge, IAR Systems</p>	<p><b>The (Software) Doctor is in...Software Vital Signs for Managing the Development of Your Embedded Software</b> Prof. Robert Oshana, NXP Semiconductors</p>	<p><b>Tips and Tricks for Debugging</b> Greg Davis, Green Hills Software</p>	<p><b>RADAR Signal Processing on an Embedded System Using the Xilinx Zynq Platform</b> Prof. Frank Kesel, Hochschule Pforzheim</p>
<p><b>Building Trust: Evaluating Platform Security Architecture (PSA)</b> Robert Coombs, ARM</p>	<p><b>Miscompilation – A Thing of the Past</b> Dr. Daniel Kästner, AbsInt Angewandte Informatik</p>		<p><b>Lowering Software Development Costs by Using Arm Cortex-M Processors in an FPGA</b> Phillip Burr, ARM</p>
<p><b>Secure and Scalable FW Upgrade Mechanisms in the IoT Domain</b> Øyvind Rønningstad, Nordic Semiconductor</p>	<p><b>Uncovering Real-Time Bugs with Specialized RTOS Tools</b> Jean Labrosse, Silicon Labs</p>	<p><b>Simplify Multi-core Debugging in Your SoC Development Workflow</b> Dr. Shawn Prestridge, IAR Systems</p>	<p><b>Custom RF SoC Have Never Been this Easy</b> Edel Griffith, Adesto Technologies</p>
Coffee Break			
<p><b>Security and Licensing for IoT Devices</b> Guenther Fischer, Wibu-Systems</p>	<p><b>Safety, Security, and Compiler Bugs</b> Greg Davis, Green Hills Software</p>	<p><b>Connectivity, Complexity &amp; the Role of Enhanced Debugging</b> Trish Messiter, Gokhan Tanyeri, Clarinox Technologies</p>	<p><b>Virtual Digital Sensor for Analog Signal Processing on SoCs</b> Vinay Bansal, Faststream Technologies</p>
<p><b>Why Should an IoT Sensor Maker Care About the Blockchain?</b> Mark Hebbel, Gerrit Fischer, Basler</p>	<p><b>The AMASS Approach for Assurance and Certification of Critical Systems</b> Gaël Blondelle, Eclipse Foundation Europe</p>		<p><b>High Speed Communication: Everything Serial</b> Dirk van den Heuvel, Topic Embedded Products</p>

Program is subject to change (as at 07.01.2019)

# CONFERENCE PROGRAM

## TUESDAY, FEBRUARY 26, 2019

	Class 3.1: The Robert Berger Class – Embedded Linux	Class 5.1: Ultra Low Power Class	Class 6.1: The Bruce Douglass Class 1 – Modeling
09:30-10:30	<b>Embedded Linux a Crash Course</b> Robert Berger, Reliable Embedded Systems	<b>Ultra Low Power Hands-on Workshop</b> Herman Roebbers, Altran	Model-Based Interface Control Documents
10:30-11:00			Improving System Requirements with Use Case Models
11:30-12:30			Everything you Always Wanted to Know About Flowcharts and Activity Diagrams
14:30-15:30			Advanced Behavioral Modeling with State Machines
16:00-17:00			Data Modeling for Systems Engineering and System Specification
17:00-17:30			The Tao of SysML Dr. Bruce Douglass, IBM
			-fully booked-

## WEDNESDAY, FEBRUARY 27, 2019

	Class 3.2: Embedded Android Workshop	Class 3.3: Linux Hands-on Workshop with BeagleBoard.org PocketBeagle	Class 4.1: The ESCRYPt Class	
09:30-10:30	<b>Embedded Android Workshop</b> Karim Yaghmour, Opersys		<b>The ESCRYPt Class – Security for a Globally Connected Vehicle</b> ESCRYPt, et.al.	
10:30-11:00				
11:00-11:30				
11:30-12:00				
12:00-12:30				
14:30-15:30				<b>Getting Started with PocketBeagle from BeagleBoard.org – A Hands-On Coding with Embedded Linux Workshop</b>
15:30-16:00				Jason Kridner, Texas Instruments & BeagleBoard.org Foundation
16:00-17:30				

## THURSDAY, FEBRUARY 28, 2019

	Class 3.4: The Mc Guire Class: Introduction to Linux Kernel Tools	Class 4.2: Hands on Side Channel Power Analysis	Class 6.3: The Bruce Douglass Class 3 Safety & Security
09:30-10:15	<b>OSADL: Introduction to Linux Kernel Tools</b> Prof. Nicholas Mc Guire, Markus Kreidl, OSADL  powered by 		Safety Analysis for Embedded Systems Development
10:15-10:30			Safety Design for Embedded Systems Development
10:30-11:00			
11:00-11:15			
11:30-12:00			<b>Model-Based Systems Engineering for Cybersecurity</b> Dr. Bruce Douglass, IBM
12:00-12:30			
13:30-16:30		<b>Hands on Side Channel Power Analysis</b> Dr. Colin O'Flynn, NewAE Technology/Dalhousie University	



Please tick:

**CLASSES**

**embedded world Conference 2019**

	Tuesday, Feb 26, 2019		Wednesday, Feb 27, 2019		Thursday, Feb 28, 2019	
	am	pm	am	pm	am	pm
<b>Class 3.1:</b> The Robert Berger Class: Embedded Linux – a Crash Course	fully booked					
<b>Class 3.2:</b> Embedded Android Workshop			☐			
<b>Class 3.3:</b> Linux Hands-on Workshop with BeagleBoard.org PocketBeagle				☐		
<b>Class 3.4:</b> The Mc Guire Class: Introduction to Linux Kernel Tools					☐	
<b>Class 4.1:</b> The ESCRYPT Class			☐			
<b>Class 4.2:</b> Hands on Side Channel Power Analysis						☐
<b>Class 5.1:</b> Ultra Low Power Class	☐					
<b>Class 5.2:</b> RISC-V Workshop			☐			
<b>Class 6.1:</b> The Bruce Douglass Class 1 Modeling	☐					
<b>Class 6.2:</b> The Bruce Douglass Class 2 Agile			☐			
<b>Class 6.3:</b> The Bruce Douglass Class 3 Safety & Security					☐	
<b>Class 6.4:</b> The Greg Davis Class C / C++					☐	

Class Fees	Early Rate until January 17, 2019	Late Rate from January 18, 2019
Half Day Class	EUR 380,-	EUR 440,-
Full Day Class	EUR 570,-	EUR 650,-

Conference Fees	Early Rate until January 17, 2019	Late Rate from January 18, 2019
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2 Conference Blocks	EUR 445,-	EUR 500,-
3 Conference Blocks	EUR 560,-	EUR 640,-
4 Conference Blocks	EUR 660,-	EUR 750,-
5 Conference Blocks	EUR 745,-	EUR 845,-
Full Conference (Classes excluded)	EUR 790,-	EUR 910,-

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## SESSIONS

### embedded world Conference 2019

	Tuesday, Feb 26, 2019		Wednesday, Feb 27, 2019		Thursday, Feb 28, 2019	
	Block 1 am	Block 2 pm	Block 3 am	Block 4 pm	Block 5 am	Block 6 pm
Session 1.1 I/II: Internet of Things I/II			<input type="checkbox"/>	<input type="checkbox"/>		
Session 1.2: Internet of Things III					<input type="checkbox"/>	
Session 1.3: Internet of Things IV OPC UA I4.0						<input type="checkbox"/>
Session 2.1: Communication I CAN	<input type="checkbox"/>					
Session 2.2: Communication II Bluetooth	<input type="checkbox"/>					
Session 2.3: Communication III Real-Time & TSN		<input type="checkbox"/>				
Session 2.4: Communication IV Wireless Physical & Design Aspects			<input type="checkbox"/>			
Session 2.5: Communication V Wireless Multiprotocol				<input type="checkbox"/>		
Session 2.6 I/II: NB-IoT & LPWA I/II					<input type="checkbox"/>	<input type="checkbox"/>
Session 2.7: Communication VI Wireless Localization						<input type="checkbox"/>
Session 2.8 I/II: Wireless Power I/II					<input type="checkbox"/>	<input type="checkbox"/>
Session 3.1: OS Basics	<input type="checkbox"/>					
Session 3.2: OSADL		<input type="checkbox"/>				
Session 3.3: Linux			<input type="checkbox"/>			
Session 3.4: Virtualization				<input type="checkbox"/>		
Session 3.5: OS-Security					<input type="checkbox"/>	
Session 4.1 I/II: HW-based Security I/II	<input type="checkbox"/>	<input type="checkbox"/>				
Session 4.2: Functional Safety	<input type="checkbox"/>					
Session 4.3 I/II: Security Architectures & Hacking I/II			<input type="checkbox"/>	<input type="checkbox"/>		
Session 4.4 I/II: Securing IoT I/II					<input type="checkbox"/>	<input type="checkbox"/>
Session 5.1: RISC-V I Overview	<input type="checkbox"/>					
Session 5.2: RISC-V II Security		<input type="checkbox"/>				
Session 5.3: RISC-V III System		<input type="checkbox"/>				
Session 5.4: Power Supply				<input type="checkbox"/>		
Session 6.1: SW-Engineering I Languages & Standards	<input type="checkbox"/>					
Session 6.2 I/II: MISRA I/II	<input type="checkbox"/>	<input type="checkbox"/>				
Session 6.3: Software Engineering II Design & Modeling			<input type="checkbox"/>			
Session 6.4: Software Engineering III Software Quality I				<input type="checkbox"/>		
Session 6.5: Software Engineering IV Development Process					<input type="checkbox"/>	
Session 6.6: Software Engineering V Software Quality II						<input type="checkbox"/>
Session 6.7: Software Engineering VI Software Testing					<input type="checkbox"/>	
Session 6.8: Software Engineering VII Software Debugging						<input type="checkbox"/>
Session 7.1 I/II: Embedded Vision I/II	<input type="checkbox"/>	<input type="checkbox"/>				
Session 8.1: Intelligent Systems I Applications	<input type="checkbox"/>					
Session 8.2: Intelligent Systems II Hardware		<input type="checkbox"/>				
Session 8.3: Intelligent Systems III Autonomous Driving			<input type="checkbox"/>			
Session 8.4: Intelligent Systems IV Development Methods				<input type="checkbox"/>		
Session 9.1: Embedded GUI & HMI		<input type="checkbox"/>				
Session 10.1: SoC I Analog Circuits & Solutions			<input type="checkbox"/>			
Session 10.2 I/II: SoC II EDA I/II			<input type="checkbox"/>	<input type="checkbox"/>		
Session 10.3: SoC III Complex ICs & System Solutions					<input type="checkbox"/>	
Session 10.4: SoC IV ICs & IPs						<input type="checkbox"/>

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- The attendance fee includes participation on the booked conference days, proceedings, refreshments and free admission to the embedded world 2019 Exhibition. If morning and afternoon blocks/classes are booked, lunch is also included for that day.
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